

ABSTRACT OF THE DISCLOSURE

EPOXY RESIN COMPOSITION

An epoxy resin composition for encapsulating a semiconductor, which is free from halogen and antimony and has excellent soldering crack resistance and high-temperature storage life without lowering the flame-retardancy, and which comprises as essential components (A) an epoxy resin, (B) a phenol resin curing agent, (C) a curing accelerator, (D) an inorganic filler and (E) a red phosphorus-based flame-retardant, wherein the ratio of (a) the number of epoxy groups of the epoxy resin to (b) the number of phenolic hydroxyl groups of the phenol resin curing agent $[(a)/(b)]$ is 0.8 to 1.2, the amount of the inorganic filler (D) contained in the epoxy resin composition is 70 to 90% by weight based on the total weight of the epoxy resin composition and the cured product of the epoxy resin composition has a glass transition temperature of 100 to 160°C and a linear expansion coefficient at 25°C of 0.8 to $1.8 \times 10^{-5}/^{\circ}\text{C}$.

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